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Claim 1. (Twice Amended) A package for containing electronic components, the package comprising:
a first circuitized card;
a second circuitized card;
an interposer interposed between the first and second circuitized cards, the interposer comprising a circuitized card and having an opening, the opening of the interposer and the first and second circuitized card forming a cavity for containing at least one electronic component,
wherein the first circuitized card has a bottom surface and there is at least one component mounted to the bottom surface.

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Claim 15. (Amended) The package of claim 1 wherein the first circuitized card has a top surface, the second circuitized card has a top surface and a bottom surface, and there is at least one component on the top surface of the first circuitized card, and there is at least one component on the top surface of the second circuitized card.

Claim 20. (Twice Amended) A package for containing electronic components, the package comprising:

a first circuitized card having a top surface and a bottom surface;
a second circuitized card having a top surface and a bottom surface;
an interposer having an opening, a top surface, and a bottom surface, the interposer being electrically connected to the first circuitized card and the second circuitized card through a first and second set of connections, the first set of connections being interposed between the bottom surface of the first circuitized card and the top surface of the interposer, the second set of connections being interposed between the bottom surface of the interposer and the top surface of the second circuitized card, wherein the bottom surface of the second circuitized card has a third set of connections for attaching the second circuitized card to a system card, and wherein the opening in the interposer, the bottom surface of the first circuitized card and the top surface of the second circuitized card forms a cavity for containing at least one electronic component.

Please add the following new claim:

Claim 53 (New) A package for containing electronic components, the package comprising:

a first circuitized card;
a second circuitized card;
an interposer interposed between the first and second circuitized cards, the interposer having an opening, the opening of the interposer and the first and second circuitized card forming a cavity for containing at least one electronic component
wherein the interposer, first circuitized card, and second circuitized card are circuitized multi-layer organic laminate cards.